

# FMBA56

## PNP Multi-Chip General-Purpose Amplifier

### Description

This device is designed for general-purpose amplifier applications at collector currents to 300 mA. Sourced from Process 73.

### Block Diagram

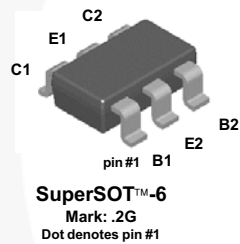


Figure 1. Device Package

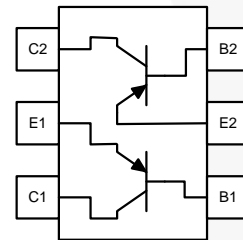


Figure 2. Internal Connections

### Ordering Information

Part Number	Marking	Package	Packing Method
FMB200	.2G	SSOT 6L	Tape and Reel

## Absolute Maximum Ratings<sup>(1),(2)</sup>

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter	Value	Unit
$V_{CES}$	Collector-Emitter Voltage	-80	V
$V_{CBO}$	Collector-Base Voltage	-80	V
$V_{EBO}$	Emitter-Base Voltage	-4	V
$I_C$	Collector Current - Continuous	-500	mA
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

### Notes:

- These ratings are based on a maximum junction temperature of  $150^\circ\text{C}$ .
- These are steady-state limits. Fairchild Semiconductor should be consulted on applications involving pulsed or low-duty cycle operations.

## Thermal Characteristics<sup>(3)</sup>

Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter	Max.	Unit
$P_D$	Total Device Dissipation	700	mW
	Derate Above $25^\circ\text{C}$	5.6	$\text{mW}/^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	180	$^\circ\text{C}/\text{W}$

### Note:

- PCB size: FR-4  $76 \times 114 \times 1.57 \text{ mm}^3$  (3.0 inch x 4.5 inch x 0.062 inch) with minimum land pattern size.

## Electrical Characteristics<sup>(4)</sup>

Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{CEO}$	Collector-Emitter Breakdown Voltage <sup>(4)</sup>	$I_C = -1.0 \text{ mA}, I_E = 0$	-80			V
$BV_{CBO}$	Collector-Base Breakdown Voltage	$I_C = -100 \mu\text{A}, I_B = 0$	-80			V
$BV_{EBO}$	Emitter-Base Breakdown Voltage	$I_E = -100 \mu\text{A}, I_C = 0$	-4.0			V
$I_{CEO}$	Collector Cut-Off Current	$V_{CE} = -60 \text{ V}, I_B = 0$			-0.1	$\mu\text{A}$
$I_{CBO}$	Collector Cut-Off Current	$V_{CB} = -80 \text{ V}, I_E = 0$			-0.1	$\mu\text{A}$
$h_{FE}$	DC Current Gain	$I_C = -10 \text{ mA}, V_{CE} = -1.0 \text{ V}$	100			
		$I_C = -100 \text{ mA}, V_{CE} = -1.0 \text{ V}$	100			
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C = -100 \text{ mA}, I_B = -10 \text{ mA}$			-0.25	V
$V_{BE(on)}$	Base-Emitter On Voltage	$I_C = -100 \text{ mA}, V_{CE} = -1.0 \text{ V}$			-1.2	V
$f_T$	Current Gain - Bandwidth Product	$I_C = -100 \text{ mA}, V_{CE} = -1.0 \text{ V}, f = 100 \text{ MHz}$	50			MHz

### Note:

- Pulse test: pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2.0\%$ .

## Typical Performance Characteristics

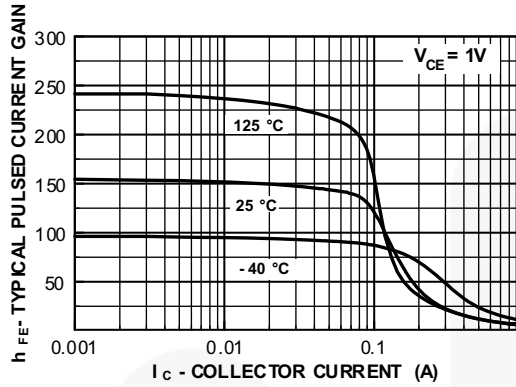


Figure 3. Typical Pulsed Current Gain vs. Collector Current

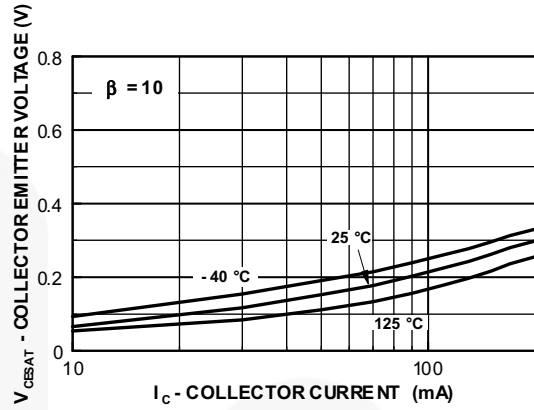


Figure 4. Collector-Emitter Saturation Voltage vs. Collector Current

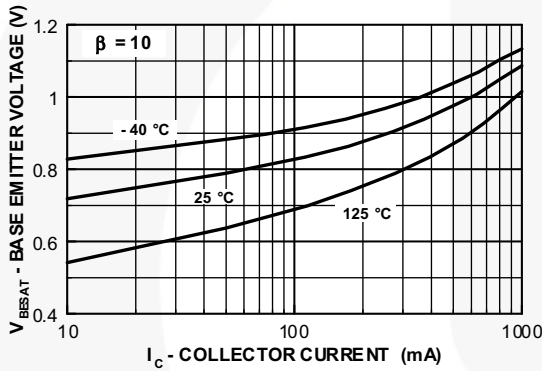


Figure 5. Base-Emitter Saturation Voltage vs. Collector Current

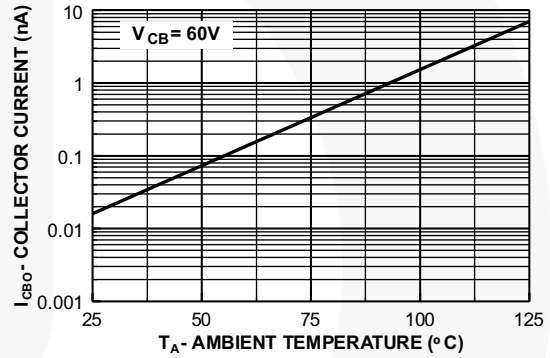


Figure 6. Collector Cut-Off Current vs. Ambient Temperature

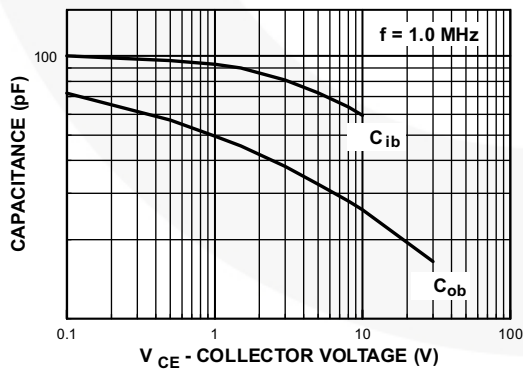


Figure 7. Input and Output Capacitance vs. Reverse Voltage

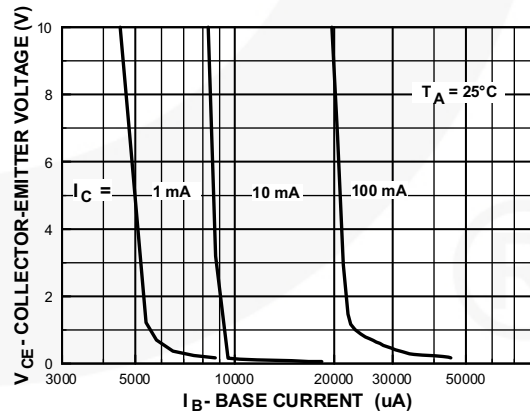


Figure 8. Collector Saturation Region

Typical Performance Characteristics (Continuous)

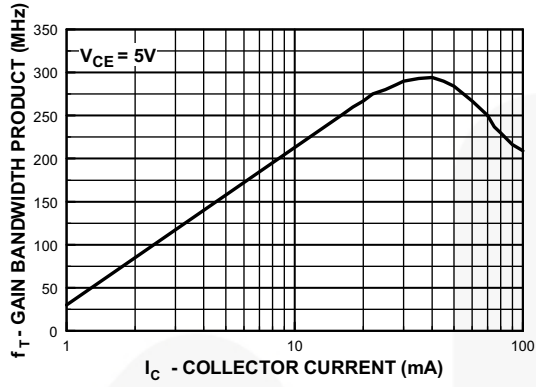


Figure 9. Gain Bandwidth Product vs. Collector Current

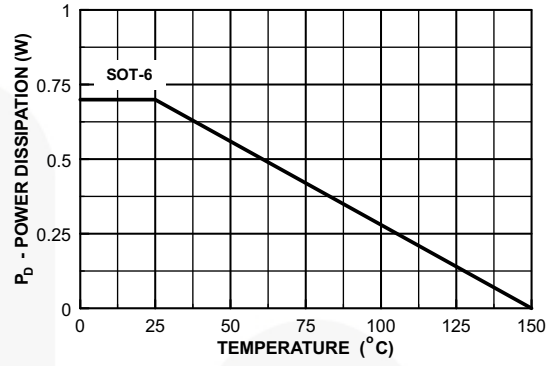


Figure 10. Power Dissipation vs. Ambient Temperature

Physical Dimensions

SSOT

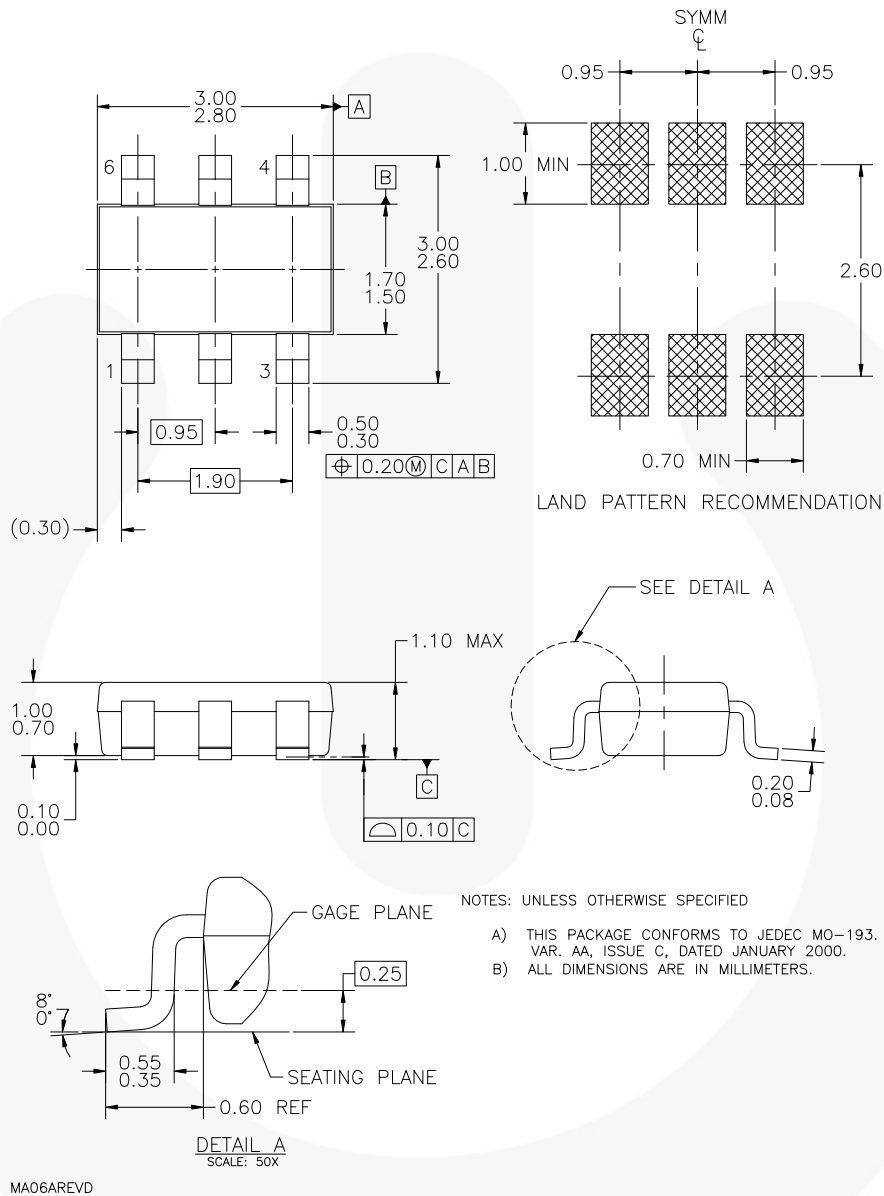


Figure 11. 6 LEAD, SUPERSOT6, JEDEC MO-193, 1.6 MM WIDE

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